

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on May 29, 2003.	
Theodore P. Cummings, Esq. Name of Attorney	403973 Registration No.
Signature of Attorney	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Application of :
Stephen Paul Zimmerman, et al. : Conf. No. 3630
Serial No.: 09/851,456 : Group Art Unit: 1761
Filed: May 8, 2001 : Examiner: Drew E. Becker
Title: SNACK CHIP HAVING IMPROVED DIP CONTAINMENT AND A
GRIP REGION

DECLARATION UNDER 37 CFR 1.131

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

I, Stephen Paul Zimmerman, hereby declare the following:

1. THAT I am a co-inventor of Claims 1-18 and 22-23 of the above-identified patent application;
2. THAT, prior to September, 1999, we completed the invention as described and claimed in the subject application in this country, a NAFTA country, or a WTO country, as evidenced by the following:
 - a.) Page 7 of the scientific notebook (Exhibit A) shows the triangular shape of the snack pieces;
 - b.) The curved-concave nature of the snack piece is shown in Exhibit B; and
 - c.) Specifics about the stacking of the snack pieces are shown in Exhibit C.

I, Stephen Paul Zimmerman, declare that all statements made herein are true to the best of my knowledge, or if made upon information and belief, are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Stephen Paul Zimmerman
Stephen Paul Zimmerman
Date: May 29, 2003

Date [REDACTED]

P&G Restricted

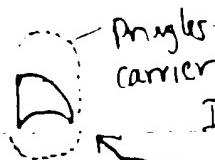
Subject ES-II Shape Development Cutter Specifications

On [REDACTED] and [REDACTED], more chips were made using the same formula and specifications given on the previous page. These chips were used in shear/use tests [REDACTED].

Chip shapes were based on specifications from the drawings below and on the next page. The chips were fired into three-dimensional shapes as follows:

Equilateral Triangle: 1) bowl-shaped

2) sinusoidal with additional curvature
(shown on the next page)



Isosceles Triangle: 1) Pringles carrier, with long axis rotated 90°

"Teardrop"/rounded triangle: 1) Pringles carrier

- measurements in millimeters

See M. Terao

8.8

Equilateral

- Ø 12.00

66.00

See M. Terao

8.8

Isosceles

Ø 12.00

62.00

Worker's Signature

See M. Terao

Date [REDACTED]

Corroborating Witness

See M. Terao

Date [REDACTED]

Exhibit K

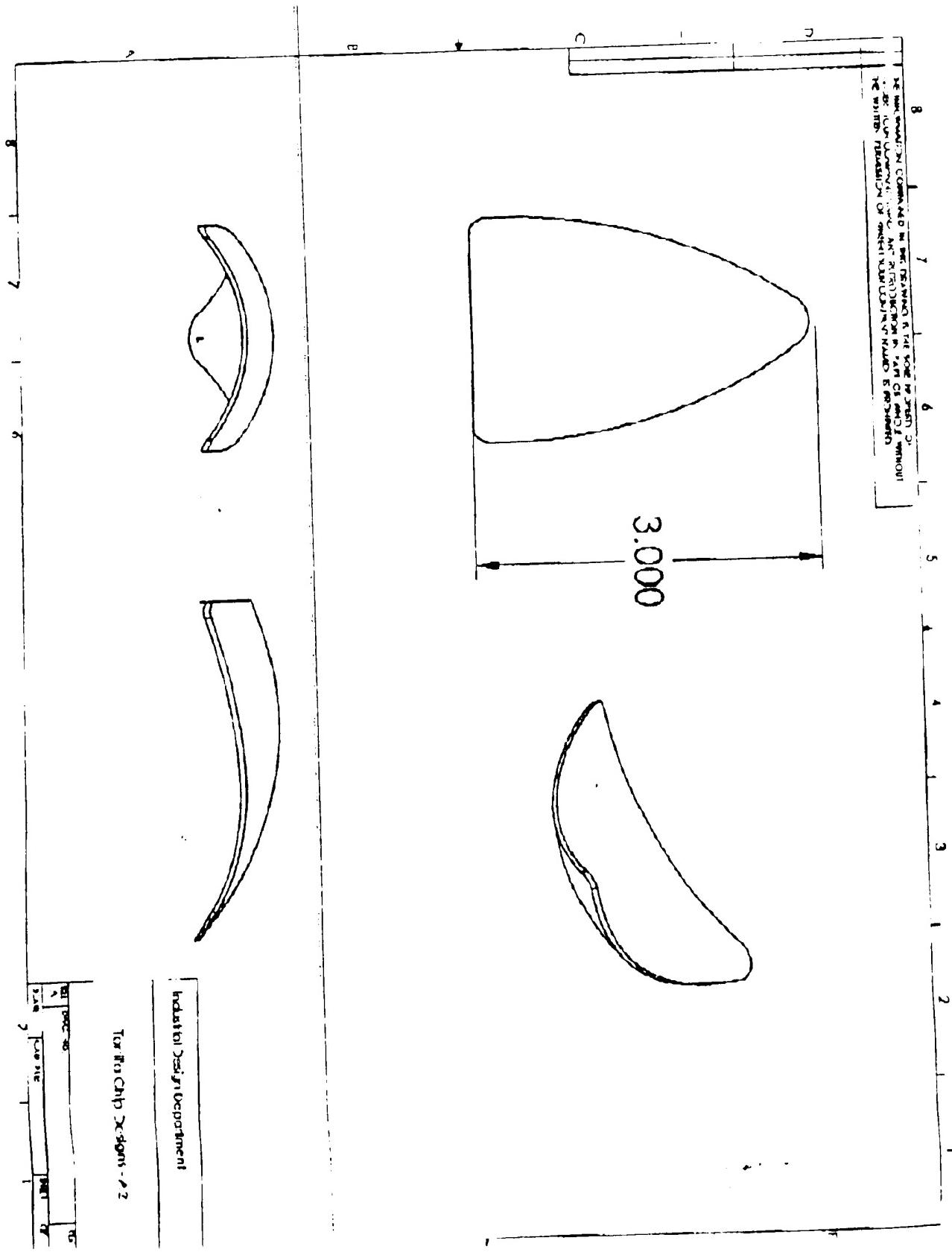


EXHIBIT C

9

Date _____

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Subject Chip Stack Height Measurements

Chips were cut to dimensions shown on previous pages and fried in carriers of the described shape.

Equilateral Bowl

Stacks of 20 chips:	Surface-to-surface
	73 mm
	70 mm
	73 mm
	63
	67

Total Ht
83 mm
82 mm
82 mm
69
74

Sigmoid Equilateral

20 chips	64
	78
	67

70
redid
measurement JMT

72
83
82

Current carrier, 90°

20 chips	64
	63
	63

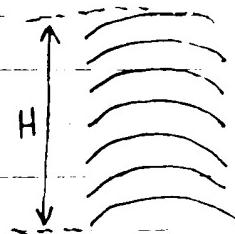
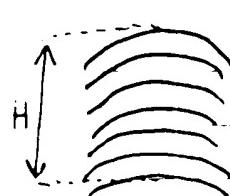
75	Redid measurement
80	76
77	JMT

Current carrier, foardig

20 chips	59
	48
15 chips	38
20 chips	56

78
65
58
76

- surface to surface : total ht :



Worker's Signature

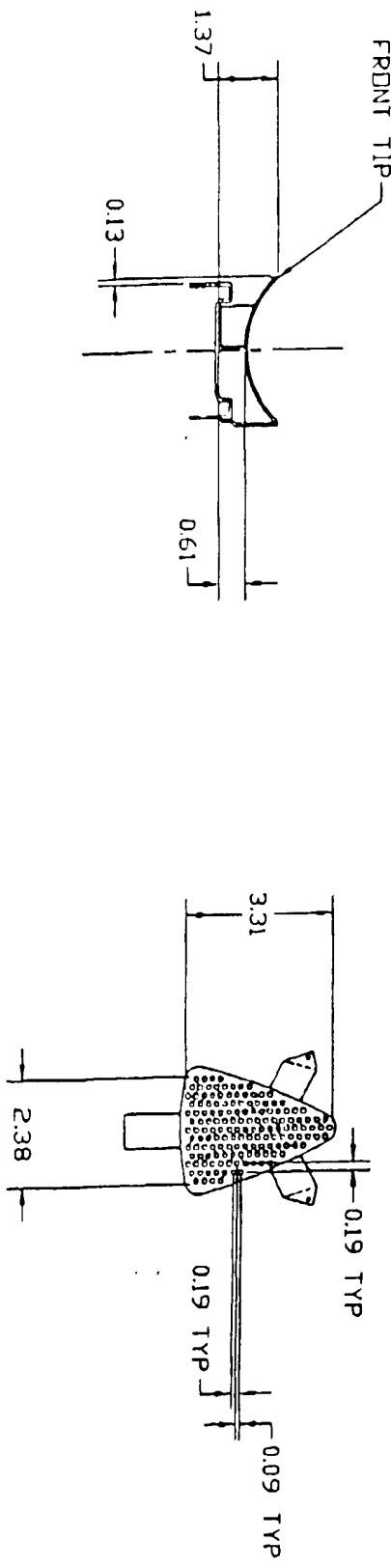
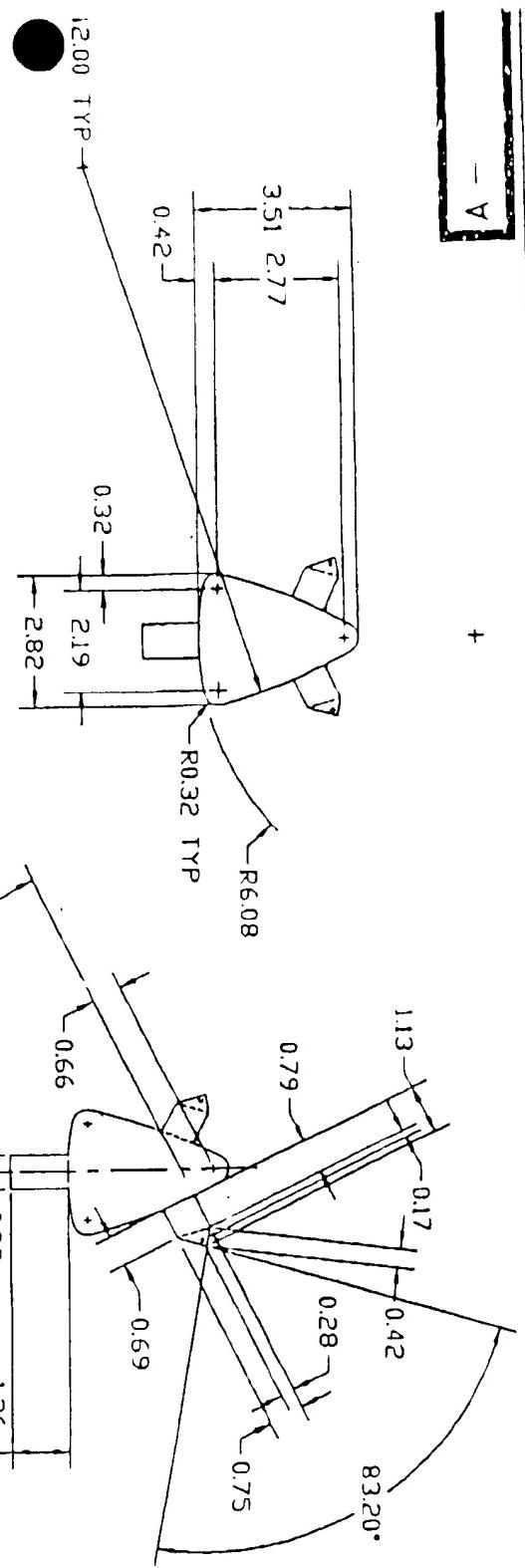
RDM Jones

Corroborating Witness

Date

Date

A -



UNITS IN INCHES	FEET AND INCHES	INCHES
MM	MM	MM
MM	MM	MM
MM	MM	MM

